

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shih-Hung Tsai</td> <td>02/25/2013</td> </tr> <tr> <td>Chun-Hsien Lin</td> <td>02/25/2013</td> </tr> <tr> <td>Chien-Ting Lin</td> <td>01/09/2013</td> </tr> </tbody> </table>		Name	Execution Date	Shih-Hung Tsai	02/25/2013	Chun-Hsien Lin	02/25/2013	Chien-Ting Lin	01/09/2013
Name	Execution Date								
Shih-Hung Tsai	02/25/2013								
Chun-Hsien Lin	02/25/2013								
Chien-Ting Lin	01/09/2013								
RECEIVING PARTY DATA									
Name:	UNITED MICROELECTRONICS CORP.								
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park								
City:	Hsin-Chu City								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13786485</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13786485				
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Application Number:	13786485								
CORRESPONDENCE DATA									
Fax Number:	7039974517								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	3027291562								
Email:	Patent.admin.uspto.cr@naipo.com								
Correspondent Name:	WINSTON HSU								
Address Line 1:	P.O.BOX 506								
Address Line 4:	Merrifield, VIRGINIA 22116								
ATTORNEY DOCKET NUMBER:	NAUP1606USA								
NAME OF SUBMITTER:	SIBYL YU								
<p>Total Attachments: 6</p> <p>source=1589031#page1.tif</p> <p>source=1589031#page2.tif</p> <p>source=1589031#page3.tif</p> <p>source=1589031#page4.tif</p> <p>source=1589031#page5.tif</p> <p>source=1589031#page6.tif</p>									

CH \$40.00 13786485

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

**Title of Invention:
METHOD FOR FORMING FIN-SHAPED STRUCTURES**

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this FEB 25 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP1606USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shih-Hung Tsai**

Date: **FEB 25 2013**

Signature: Shih-Hung Tsai

NPO#NAU-P1606-USA:0
CUST#UMCD-2012-0284

Page 2 of 6

F#NPO-P0002E-US1201
DSC0-101U017405

PATENT
REEL: 029930 FRAME: 0466

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Docket No NAUP1606USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chun-Hsien Lin**

Date:

FEB 25 2013

Signature:

Chun-Hsien Lin

NPO#NAU-P1606-USA:0
CUST#UMCD-2012-0284

Page 4 of 6

F#NPO-P0002E-US1201
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IN WITNESS WHEREOF, I have hereunto set hand and seal this JAN 09 2013 (Date of signing)

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Docket No NAUP1606USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chien-Ting Lin**

Date:

1/9/2013

Signature:

Chien-Ting Lin

NPO#NAU-P1606-USA:0
CUST#UMCD-2012-0284

Page 6 of 6

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RECORDED: 03/06/2013

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REEL: 029930 FRAME: 0470